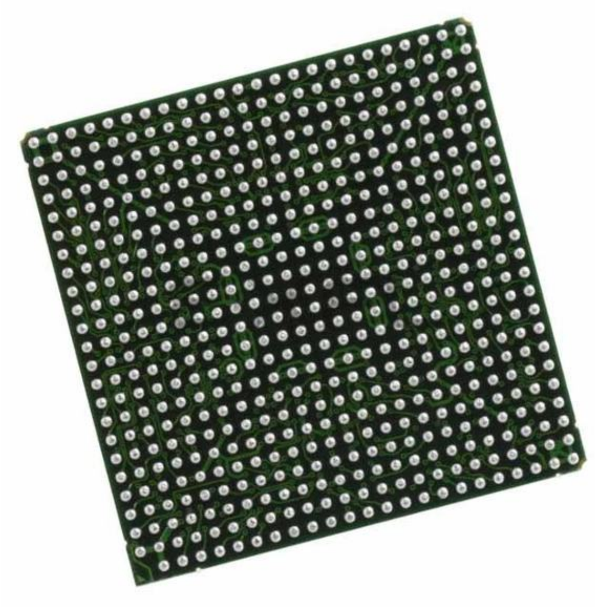
AMD Xilinx - XC2V2000-6BGG575C Datasheet



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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2688
Number of Logic Elements/Cells	-
Total RAM Bits	1032192
Number of I/O	408
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	575-BBGA
Supplier Device Package	575-BGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2v2000-6bgg575c

Table 4: **LVTTL and LVCMOS Programmable Currents (Sink and Source)**

SelectI/O-Ultra	Programmable Current (Worst-Case Guaranteed Minimum)						
LVTTL	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS33	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS25	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS18	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	n/a
LVCMOS15	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	n/a

Figure 6 shows the SSTL2, SSTL3, and HSTL configurations. HSTL can sink current up to 48 mA. (HSTL IV)

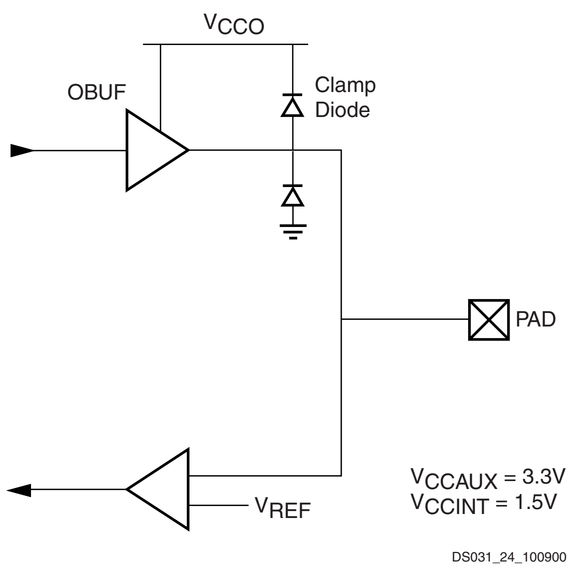


Figure 6: **SSTL or HSTL SelectI/O-Ultra Standards**

All pads are protected against damage from electrostatic discharge (ESD) and from over-voltage transients. Virtex-II uses two memory cells to control the configuration of an I/O as an input. This is to reduce the probability of an I/O configured as an input from flipping to an output when subjected to a single event upset (SEU) in space applications.

Prior to configuration, all outputs not involved in configuration are forced into their high-impedance state. The pull-down resistors and the weak-keeper circuits are inactive. The dedicated pin HSWAP_EN controls the pull-up resistors prior to configuration. By default, HSWAP_EN is set high, which disables the pull-up resistors on user I/O pins. When HSWAP_EN is set low, the pull-up resistors are activated on user I/O pins.

All Virtex-II IOBs support IEEE 1149.1 compatible Boundary-Scan testing.

Input Path

The Virtex-II IOB input path routes input signals directly to internal logic and / or through an optional input flip-flop or latch, or through the DDR input registers. An optional delay element at the D-input of the storage element eliminates pad-to-pad hold time. The delay is matched to the internal clock-distribution delay of the Virtex-II device, and when used, assures that the pad-to-pad hold time is zero.

Each input buffer can be configured to conform to any of the low-voltage signaling standards supported. In some of these standards the input buffer utilizes a user-supplied threshold voltage, V_{REF}. The need to supply V_{REF} imposes constraints on which standards can be used in the same bank. See I/O banking description.

Output Path

The output path includes a 3-state output buffer that drives the output signal onto the pad. The output and / or the 3-state signal can be routed to the buffer directly from the internal logic or through an output / 3-state flip-flop or latch, or through the DDR output / 3-state registers.

Each output driver can be individually programmed for a wide range of low-voltage signaling standards. In most signaling standards, the output High voltage depends on an externally supplied V_{CCO} voltage. The need to supply V_{CCO} imposes constraints on which standards can be used in the same bank. See I/O banking description.

I/O Banking

Some of the I/O standards described above require V_{CCO} and V_{REF} voltages. These voltages are externally supplied and connected to device pins that serve groups of IOB blocks, called banks. Consequently, restrictions exist about which I/O standards can be combined within a given bank.

Eight I/O banks result from dividing each edge of the FPGA into two banks, as shown in Figure 7 and Figure 8. Each bank has multiple V_{CCO} pins, all of which must be connected to the same voltage. This voltage is determined by the output standards in use.

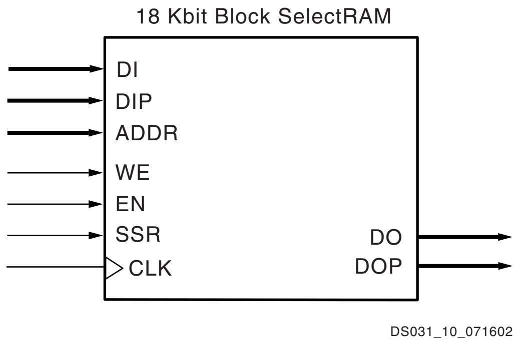


Figure 29: **18 Kbit Block SelectRAM Memory in Single-Port Mode**

Dual-Port Configuration

As a dual-port RAM, each port of block SelectRAM has access to a common 18 Kbit memory resource. These are fully synchronous ports with independent control signals for each port. The data widths of the two ports can be configured independently, providing built-in bus-width conversion.

Table 15 illustrates the different configurations available on ports A and B.

If both ports are configured in either 2K x 9-bit, 1K x 18-bit, or 512 x 36-bit configurations, the 18 Kbit block is accessible from port A or B. If both ports are configured in either 16K x 1-bit, 8K x 2-bit. or 4K x 4-bit configurations, the 16 K-bit block is accessible from Port A or Port B. All other configurations result in one port having access to an 18 Kbit memory block and the other port having access to a 16 K-bit subset of the memory block equal to 16 Kbits.

Table 15: **Dual-Port Mode Configurations**

Port A	16K x 1	16K x 1	16K x 1	16K x 1	16K x 1	16K x 1
Port B	16K x 1	8K x 2	4K x 4	2K x 9	1K x 18	512 x 36
Port A	8K x 2	8K x 2	8K x 2	8K x 2	8K x 2	
Port B	8K x 2	4K x 4	2K x 9	1K x 18	512 x 36	
Port A	4K x 4	4K x 4	4K x 4	4K x 4		
Port B	4K x 4	2K x 9	1K x 18	512 x 36		
Port A	2K x 9	2K x 9	2K x 9			
Port B	2K x 9	1K x 18	512 x 36			
Port A	1K x 18	1K x 18				
Port B	1K x 18	512 x 36				
Port A	512 x 36					
Port B	512 x 36					

Each SelectRAM memory and multiplier block is tied to four switch matrices, as shown in Figure 35.

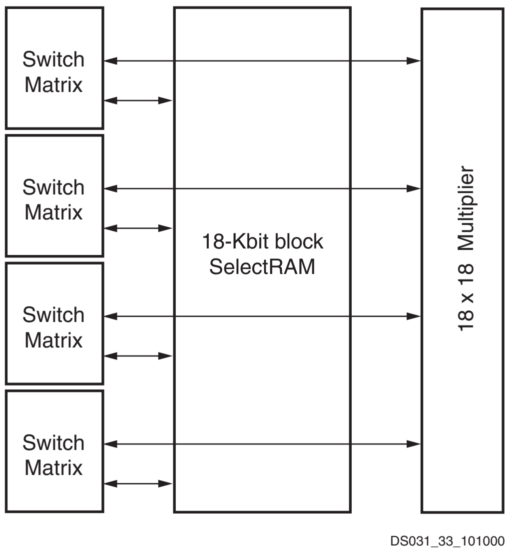


Figure 35: **SelectRAM and Multiplier Blocks**

Association With Block SelectRAM Memory

The interconnect is designed to allow SelectRAM memory and multiplier blocks to be used at the same time, but some interconnect is shared between the SelectRAM and the multiplier. Thus, SelectRAM memory can be used only up to 18 bits wide when the multiplier is used, because the multiplier shares inputs with the upper data bits of the SelectRAM memory.

This sharing of the interconnect is optimized for an 18-bit-wide block SelectRAM resource feeding the multiplier. The use of SelectRAM memory and the multiplier with an accumulator in LUTs allows for implementation of a digital signal processor (DSP) multiplier-accumulator (MAC) function, which is commonly used in finite and infinite impulse response (FIR and IIR) digital filters.

Configuration

The multiplier block is an 18-bit by 18-bit signed multiplier (2's complement). Both A and B are 18-bit-wide inputs, and the output is 36 bits. Figure 36 shows a multiplier block.

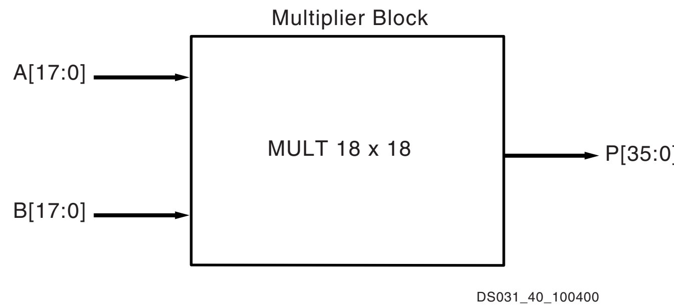


Figure 36: **Multiplier Block**

Locations / Organization

Multiplier organization is identical to the 18 Kbit SelectRAM organization, because each multiplier is associated with an 18 Kbit block SelectRAM resource.

In addition to the built-in multiplier blocks, the CLB elements have dedicated logic to implement efficient multipliers in logic. (Refer to Configurable Logic Blocks (CLBs)).

Table 20: **Multiplier Floor Plan**

Device	Columns	Multipliers	
		Per Column	Total
XC2V40	2	2	4
XC2V80	2	4	8
XC2V250	4	6	24
XC2V500	4	8	32
XC2V1000	4	10	40
XC2V1500	4	12	48
XC2V2000	4	14	56
XC2V3000	6	16	96
XC2V4000	6	20	120
XC2V6000	6	24	144
XC2V8000	6	28	168

Table 27: **Enhanced Pipelined Multiplier Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-6	-5	-4	
Setup and Hold Times Before/After Clock					
Data Inputs	$T_{MULIDCK}/T_{MULCKID}$	3.00/0.00	3.45/0.00	3.89/0.00	ns, Max
Clock Enable	$T_{MULIDCK\_CE}/T_{MULCKID\_CE}$	0.72/0.00	0.80/0.00	0.86/0.00	ns, Max
Reset	$T_{MULIDCK\_RST}/T_{MULCKID\_RST}$	0.72/0.00	0.80/0.00	0.86/0.00	ns, Max
Clock to Output Pin					
Clock to Pin 35	$T_{MULTCK1\_P35}$	3.05	3.25	3.74	ns, Max
Clock to Pin 34	$T_{MULTCK1\_P34}$	2.95	3.14	3.61	ns, Max
Clock to Pin 33	$T_{MULTCK1\_P33}$	2.85	3.04	3.49	ns, Max
Clock to Pin 32	$T_{MULTCK1\_P32}$	2.76	2.93	3.37	ns, Max
Clock to Pin 31	$T_{MULTCK1\_P31}$	2.66	2.82	3.25	ns, Max
Clock to Pin 30	$T_{MULTCK1\_P30}$	2.56	2.72	3.12	ns, Max
Clock to Pin 29	$T_{MULTCK1\_P29}$	2.47	2.61	3.00	ns, Max
Clock to Pin 28	$T_{MULTCK1\_P28}$	2.37	2.50	2.88	ns, Max
Clock to Pin 27	$T_{MULTCK1\_P27}$	2.27	2.40	2.75	ns, Max
Clock to Pin 26	$T_{MULTCK1\_P26}$	2.17	2.29	2.63	ns, Max
Clock to Pin 25	$T_{MULTCK1\_P25}$	2.08	2.18	2.51	ns, Max
Clock to Pin 24	$T_{MULTCK1\_P24}$	1.98	2.07	2.38	ns, Max
Clock to Pin 23	$T_{MULTCK1\_P23}$	1.88	1.97	2.26	ns, Max
Clock to Pin 22	$T_{MULTCK1\_P22}$	1.79	1.86	2.14	ns, Max
Clock to Pin 21	$T_{MULTCK1\_P21}$	1.69	1.75	2.02	ns, Max
Clock to Pin 20	$T_{MULTCK1\_P20}$	1.59	1.65	1.89	ns, Max
Clock to Pin 19	$T_{MULTCK1\_P19}$	1.50	1.54	1.77	ns, Max
Clock to Pin 18	$T_{MULTCK1\_P18}$	1.40	1.43	1.65	ns, Max
Clock to Pin 17	$T_{MULTCK1\_P17}$	1.30	1.33	1.52	ns, Max
Clock to Pin 16	$T_{MULTCK1\_P16}$	1.20	1.22	1.40	ns, Max
Clock to Pin 15	$T_{MULTCK1\_P15}$	1.11	1.11	1.28	ns, Max
Clock to Pin 14	$T_{MULTCK1\_P14}$	1.01	1.00	1.15	ns, Max
Clock to Pin 13	$T_{MULTCK1\_P13}$	0.91	1.00	1.15	ns, Max
Clock to Pin 12	$T_{MULTCK1\_P12}$	0.91	1.00	1.15	ns, Max
Clock to Pin 11	$T_{MULTCK1\_P11}$	0.91	1.00	1.15	ns, Max
Clock to Pin 10	$T_{MULTCK1\_P10}$	0.91	1.00	1.15	ns, Max
Clock to Pin 9	$T_{MULTCK1\_P9}$	0.91	1.00	1.15	ns, Max
Clock to Pin 8	$T_{MULTCK1\_P8}$	0.91	1.00	1.15	ns, Max
Clock to Pin 7	$T_{MULTCK1\_P7}$	0.91	1.00	1.15	ns, Max
Clock to Pin 6	$T_{MULTCK1\_P6}$	0.91	1.00	1.15	ns, Max
Clock to Pin 5	$T_{MULTCK1\_P5}$	0.91	1.00	1.15	ns, Max
Clock to Pin 4	$T_{MULTCK1\_P4}$	0.91	1.00	1.15	ns, Max
Clock to Pin 3	$T_{MULTCK1\_P3}$	0.91	1.00	1.15	ns, Max
Clock to Pin 2	$T_{MULTCK1\_P2}$	0.91	1.00	1.15	ns, Max
Clock to Pin 1	$T_{MULTCK1\_P1}$	0.91	1.00	1.15	ns, Max
Clock to Pin 0	$T_{MULTCK1\_P0}$	0.91	1.00	1.15	ns, Max

Block SelectRAM Switching Characteristics

Table 28: **Block SelectRAM Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-6	-5	-4	
Sequential Delays					
Clock CLK to DOUT output	T_{BCKO}	2.10	2.31	2.65	ns, Max
Setup and Hold Times Before Clock CLK					
ADDR inputs	T_{BACK}/T_{BCKA}	0.29/ 0.00	0.32/ 0.00	0.36/ 0.00	ns, Min
DIN inputs	T_{BDCK}/T_{BCKD}	0.29/ 0.00	0.32/ 0.00	0.36/ 0.00	ns, Min
EN input	T_{BECK}/T_{BCKE}	0.95/–0.46	1.04/–0.50	1.20/–0.58	ns, Min
RST input	T_{BRCK}/T_{BCKR}	1.31/–0.71	1.44/–0.78	1.65/–0.90	ns, Min
WEN input	T_{BWCK}/T_{BCKW}	0.57/–0.19	0.63/–0.21	0.72/–0.25	ns, Min
Clock CLK					
CLKA to CLKB setup time for different ports	T_{BCCS}	1.0	1.0	1.0	ns, min
Minimum Pulse Width, High	T_{BPWH}	1.17	1.29	1.48	ns, Min
Minimum Pulse Width, Low	T_{BPWL}	1.17	1.29	1.48	ns, Min

TBUF Switching Characteristics

Table 29: **TBUF Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-6	-5	-4	
Combinatorial Delays					
IN input to OUT output	T_{IO}	0.45	0.50	0.58	ns, Max
TRI input to OUT output high-impedance	T_{OFF}	0.44	0.48	0.55	ns, Max
TRI input to valid data on OUT output	T_{ON}	0.44	0.48	0.55	ns, Max

Virtex-II Pin-to-Pin Output Parameter Guidelines

All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted.

Global Clock Input to Output Delay for LVTTL, 12 mA, Fast Slew Rate, *With* DCM

Table 34: **Global Clock Input to Output Delay for LVTTL, 12 mA, Fast Slew Rate, *With* DCM**

Description	Symbol	Device	Speed Grade			Units
			-6	-5	-4	
LVTTL Global Clock Input to Output delay using Output flip-flop, 12 mA, Fast Slew Rate, *with* DCM. For data *output* with different standards, adjust the delays with the values shown in IOB Output Switching Characteristics Standard Adjustments, page 14.						
Global Clock and OFF with DCM	$T_{ICKOFDCM}$	XC2V40	1.10	1.28	1.48	ns
		XC2V80	1.10	1.28	1.48	ns
		XC2V250	1.10	1.28	1.48	ns
		XC2V500	1.10	1.28	1.48	ns
		XC2V1000	1.10	1.28	1.48	ns
		XC2V1500	1.10	1.28	1.48	ns
		XC2V2000	1.10	1.28	1.48	ns
		XC2V3000	1.19	1.38	1.59	ns
		XC2V4000	1.19	1.38	1.59	ns
		XC2V6000	1.64	1.88	2.17	ns
		XC2V8000		1.88	2.17	ns

Notes:
1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with test setup shown in Figure 1. For other I/O standards, see Table 19.

Table 6: **FG256/FGG256 BGA — XC2V40, XC2V80, XC2V250, XC2V500, and XC2V1000**

Bank	Pin Description	Pin Number	No Connect in XC2V40	No Connect in XC2V80
1	IO_L92P_1	E11	NC	NC
1	IO_L05N_1	A11	NC	NC
1	IO_L05P_1	B11	NC	NC
1	IO_L04N_1	C11	NC	NC
1	IO_L04P_1/VREF_1	D11	NC	NC
1	IO_L03N_1/VRP_1	A12		
1	IO_L03P_1/VRN_1	B12		
1	IO_L02N_1	C12		
1	IO_L02P_1	D12		
1	IO_L01N_1	B13		
1	IO_L01P_1	C13		
2	IO_L01N_2	C16		
2	IO_L01P_2	D16		
2	IO_L02N_2/VRP_2	D14		
2	IO_L02P_2/VRN_2	D15		
2	IO_L03N_2	E13		
2	IO_L03P_2/VREF_2	E14		
2	IO_L04N_2	E15	NC	
2	IO_L04P_2	E16	NC	
2	IO_L06N_2	F13	NC	
2	IO_L06P_2	F14	NC	
2	IO_L43N_2	F15	NC	NC
2	IO_L43P_2	F16	NC	NC
2	IO_L45N_2	F12	NC	NC
2	IO_L45P_2/VREF_2	G12	NC	NC
2	IO_L91N_2	G13	NC	
2	IO_L91P_2	G14	NC	
2	IO_L93N_2	G15	NC	
2	IO_L93P_2/VREF_2	G16	NC	
2	IO_L94N_2	H13		
2	IO_L94P_2	H14		
2	IO_L96N_2	H15		
2	IO_L96P_2	H16		

Table 8: **FG676/FGG676 BGA — XC2V1500, XC2V2000, and XC2V3000**

Bank	Pin Description	Pin Number	No Connect in XC2V1500	No Connect in XC2V2000
2	IO_L96P_2	N23		
3	IO_L96N_3	N26		
3	IO_L96P_3	P26		
3	IO_L94N_3	P23		
3	IO_L94P_3	P22		
3	IO_L93N_3/VREF_3	P19		
3	IO_L93P_3	N19		
3	IO_L91N_3	P21		
3	IO_L91P_3	P20		
3	IO_L78N_3	R26	NC	
3	IO_L78P_3	R25	NC	
3	IO_L76N_3	R20	NC	
3	IO_L76P_3	R19	NC	
3	IO_L75N_3/VREF_3	R24	NC	
3	IO_L75P_3	R23	NC	
3	IO_L73N_3	R22	NC	
3	IO_L73P_3	R21	NC	
3	IO_L72N_3	T26		
3	IO_L72P_3	T25		
3	IO_L70N_3	T20		
3	IO_L70P_3	T19		
3	IO_L69N_3/VREF_3	T24		
3	IO_L69P_3	T23		
3	IO_L67N_3	T22		
3	IO_L67P_3	T21		
3	IO_L54N_3	U26		
3	IO_L54P_3	V26		
3	IO_L52N_3	U24		
3	IO_L52P_3	U23		
3	IO_L51N_3/VREF_3	U22		
3	IO_L51P_3	U21		
3	IO_L49N_3	V25		
3	IO_L49P_3	V24		
3	IO_L48N_3	V23		
3	IO_L48P_3	V22		
3	IO_L46N_3	W26		

Table 8: **FG676/FGG676 BGA — XC2V1500, XC2V2000, and XC2V3000**

Bank	Pin Description	Pin Number	No Connect in XC2V1500	No Connect in XC2V2000
6	IO_L52N_6	U1		
6	IO_L54P_6	U7		
6	IO_L54N_6	T7		
6	IO_L67P_6	U4		
6	IO_L67N_6	U3		
6	IO_L69P_6	U6		
6	IO_L69N_6/VREF_6	U5		
6	IO_L70P_6	T5		
6	IO_L70N_6	T6		
6	IO_L72P_6	T8		
6	IO_L72N_6	R8		
6	IO_L73P_6	T2	NC	
6	IO_L73N_6	T1	NC	
6	IO_L75P_6	T4	NC	
6	IO_L75N_6/VREF_6	T3	NC	
6	IO_L76P_6	R6	NC	
6	IO_L76N_6	R5	NC	
6	IO_L78P_6	R4	NC	
6	IO_L78N_6	R3	NC	
6	IO_L91P_6	R2		
6	IO_L91N_6	R1		
6	IO_L93P_6	R7		
6	IO_L93N_6/VREF_6	P7		
6	IO_L94P_6	P6		
6	IO_L94N_6	P5		
6	IO_L96P_6	P4		
6	IO_L96N_6	P3		
7	IO_L96P_7	P1		
7	IO_L96N_7	N1		
7	IO_L94P_7	N4		
7	IO_L94N_7	N5		
7	IO_L93P_7/VREF_7	N6		
7	IO_L93N_7	N7		
7	IO_L91P_7	P8		
7	IO_L91N_7	N8		
7	IO_L78P_7	M1	NC	

Table 8: **FG676/FGG676 BGA — XC2V1500, XC2V2000, and XC2V3000**

Bank	Pin Description	Pin Number	No Connect in XC2V1500	No Connect in XC2V2000
7	IO_L21P_7/VREF_7	F3		
7	IO_L21N_7	F2		
7	IO_L19P_7	H6		
7	IO_L19N_7	H7		
7	IO_L06P_7	E1		
7	IO_L06N_7	E2		
7	IO_L04P_7	D1		
7	IO_L04N_7	D2		
7	IO_L03P_7/VREF_7	C1		
7	IO_L03N_7	C2		
7	IO_L02P_7/VRN_7	E3		
7	IO_L02N_7/VRP_7	E4		
7	IO_L01P_7	G5		
7	IO_L01N_7	F4		
0	VCCO_0	J13		
0	VCCO_0	J12		
0	VCCO_0	J11		
0	VCCO_0	H10		
0	VCCO_0	H9		
0	VCCO_0	B10		
0	VCCO_0	B7		
1	VCCO_1	B17		
1	VCCO_1	J16		
1	VCCO_1	J15		
1	VCCO_1	J14		
1	VCCO_1	H18		
1	VCCO_1	H17		
1	VCCO_1	B20		
2	VCCO_2	N18		
2	VCCO_2	M18		
2	VCCO_2	L18		
2	VCCO_2	K25		
2	VCCO_2	K19		
2	VCCO_2	J19		
2	VCCO_2	G25		
3	VCCO_3	Y25		

Table 8: **FG676/FGG676 BGA — XC2V1500, XC2V2000, and XC2V3000**

Bank	Pin Description	Pin Number	No Connect in XC2V1500	No Connect in XC2V2000
NA	GND	R12		
NA	GND	R11		
NA	GND	R10		
NA	GND	P25		
NA	GND	P17		
NA	GND	P16		
NA	GND	P15		
NA	GND	P14		
NA	GND	P13		
NA	GND	P12		
NA	GND	P11		
NA	GND	P10		
NA	GND	P2		
NA	GND	N25		
NA	GND	N17		
NA	GND	N16		
NA	GND	N15		
NA	GND	N14		
NA	GND	N13		
NA	GND	N12		
NA	GND	N11		
NA	GND	N10		
NA	GND	N2		
NA	GND	M17		
NA	GND	M16		
NA	GND	M15		
NA	GND	M14		
NA	GND	M13		
NA	GND	M12		
NA	GND	M11		
NA	GND	M10		
NA	GND	L17		
NA	GND	L16		
NA	GND	L15		
NA	GND	L14		
NA	GND	L13		
NA	GND	L12		

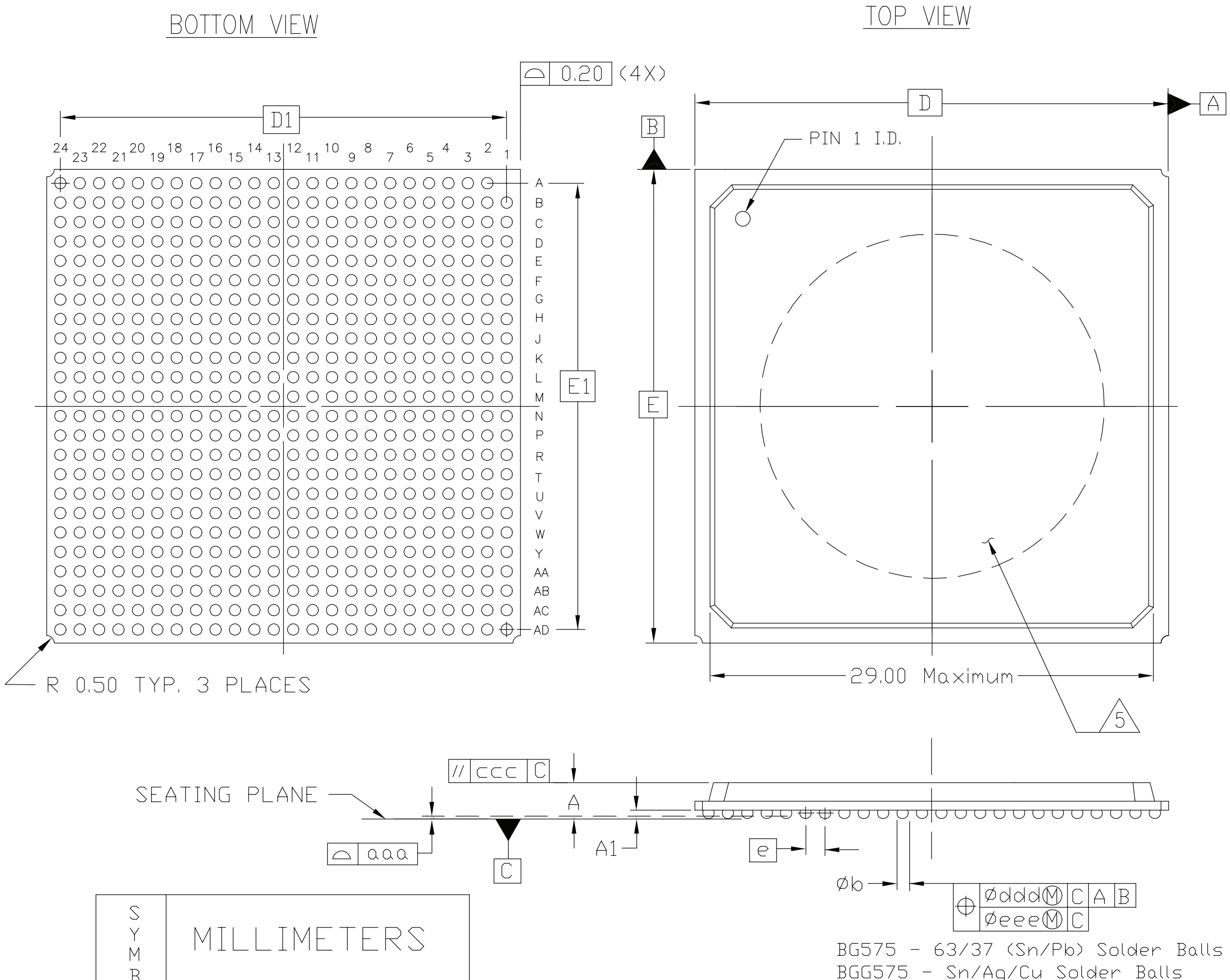
Table 9: **BG575/BGG575 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in XC2V1000	No Connect in XC2V1500
0	IO_L69P_0/VREF_0	B9	NC	
0	IO_L70N_0	F10	NC	
0	IO_L70P_0	E10	NC	
0	IO_L72N_0	A10	NC	
0	IO_L72P_0	A11	NC	
0	IO_L73N_0	C10	NC	NC
0	IO_L73P_0	B10	NC	NC
0	IO_L91N_0/VREF_0	D11		
0	IO_L91P_0	C11		
0	IO_L92N_0	G11		
0	IO_L92P_0	E11		
0	IO_L93N_0	C12		
0	IO_L93P_0	B12		
0	IO_L94N_0/VREF_0	E12		
0	IO_L94P_0	D12		
0	IO_L95N_0/GCLK7P	G12		
0	IO_L95P_0/GCLK6S	F12		
0	IO_L96N_0/GCLK5P	H11		
0	IO_L96P_0/GCLK4S	H12		
1	IO_L96N_1/GCLK3P	A13		
1	IO_L96P_1/GCLK2S	A14		
1	IO_L95N_1/GCLK1P	B13		
1	IO_L95P_1/GCLK0S	C13		
1	IO_L94N_1	D13		
1	IO_L94P_1/VREF_1	E13		
1	IO_L93N_1	F13		
1	IO_L93P_1	G13		
1	IO_L92N_1	H13		
1	IO_L92P_1	H14		
1	IO_L91N_1	C14		
1	IO_L91P_1/VREF_1	D14		
1	IO_L73N_1	E14	NC	NC
1	IO_L73P_1	G14	NC	NC
1	IO_L72N_1	A15	NC	
1	IO_L72P_1	A16	NC	

Table 9: **BG575/BGG575 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in XC2V1000	No Connect in XC2V1500
4	IO_L91P_4	AB14		
4	IO_L92N_4	V14		
4	IO_L92P_4	Y14		
4	IO_L93N_4	AB13		
4	IO_L93P_4	AC13		
4	IO_L94N_4/VREF_4	Y13		
4	IO_L94P_4	AA13		
4	IO_L95N_4/GCLK3S	V13		
4	IO_L95P_4/GCLK2P	W13		
4	IO_L96N_4/GCLK1S	U14		
4	IO_L96P_4/GCLK0P	U13		
5	IO_L96N_5/GCLK7S	AD12		
5	IO_L96P_5/GCLK6P	AD11		
5	IO_L95N_5/GCLK5S	AC12		
5	IO_L95P_5/GCLK4P	AB12		
5	IO_L94N_5	AA12		
5	IO_L94P_5/VREF_5	Y12		
5	IO_L93N_5	W12		
5	IO_L93P_5	V12		
5	IO_L92N_5	U12		
5	IO_L92P_5	U11		
5	IO_L91N_5	AB11		
5	IO_L91P_5/VREF_5	AA11		
5	IO_L73N_5	Y11	NC	NC
5	IO_L73P_5	V11	NC	NC
5	IO_L72N_5	AD10	NC	
5	IO_L72P_5	AD9	NC	
5	IO_L70N_5	AC10	NC	
5	IO_L70P_5	AB10	NC	
5	IO_L69N_5/VREF_5	Y10	NC	
5	IO_L69P_5	W10	NC	
5	IO_L67N_5	V10	NC	
5	IO_L67P_5	U10	NC	
5	IO_L54N_5	AC9		
5	IO_L54P_5	AB9		

BG575/BGG575 Standard BGA Package Specifications (1.27mm pitch)



SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A		2.33	2.60
A_1	0.50	0.60	0.70
D/E	31.00 BSC		
D_1/E_1	29.21 REF		
e	1.27BSC		
Øb	0.60	0.75	0.90
aaa			0.20
ccc			0.35
ddd			0.30
eee			0.15
M	24		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M−1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS−034−BAN−1 (DEPOPULATED)
4. NO SOLDER BALL AND LAND ON A1.

5. HEAT SINK OPTION

575−BALL MOLDED BGA (BG575/BGG575)

Figure 5: **BG575/BGG575 Standard BGA Package Specifications**

Table 11: **FF896 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
7	IO_L95N_7	R24		
7	IO_L94P_7	R29		
7	IO_L94N_7	T29		
7	IO_L93P_7/VREF_7	R27		
7	IO_L93N_7	P27		
7	IO_L92P_7	R23		
7	IO_L92N_7	P23		
7	IO_L91P_7	N30		
7	IO_L91N_7	P30		
7	IO_L78P_7	P26	NC	NC
7	IO_L78N_7	R26	NC	NC
7	IO_L77P_7	R22	NC	NC
7	IO_L77N_7	P22	NC	NC
7	IO_L76P_7	N29	NC	NC
7	IO_L76N_7	P29	NC	NC
7	IO_L75P_7/VREF_7	N27	NC	NC
7	IO_L75N_7	N26	NC	NC
7	IO_L74P_7	P25	NC	NC
7	IO_L74N_7	N25	NC	NC
7	IO_L73P_7	L30	NC	NC
7	IO_L73N_7	M30	NC	NC
7	IO_L72P_7	L28	NC	
7	IO_L72N_7	M28	NC	
7	IO_L71P_7	N24	NC	
7	IO_L71N_7	M24	NC	
7	IO_L70P_7	L29	NC	
7	IO_L70N_7	M29	NC	
7	IO_L69P_7/VREF_7	M27	NC	
7	IO_L69N_7	L27	NC	
7	IO_L68P_7	N23	NC	
7	IO_L68N_7	M23	NC	
7	IO_L67P_7	J30	NC	
7	IO_L67N_7	K30	NC	
7	IO_L54P_7	K26		
7	IO_L54N_7	L26		
7	IO_L53P_7	M25		
7	IO_L53N_7	L25		

Table 12: **FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000**

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
4	IO_L20N_4	AJ10	
4	IO_L20P_4	AJ9	
4	IO_L21N_4	AH9	
4	IO_L21P_4/VREF_4	AH10	
4	IO_L22N_4	AN5	
4	IO_L22P_4	AN4	
4	IO_L23N_4	AE12	
4	IO_L23P_4	AE13	
4	IO_L24N_4	AM9	
4	IO_L24P_4	AL8	
4	IO_L25N_4	AP5	
4	IO_L25P_4	AP4	
4	IO_L26N_4	AG11	
4	IO_L26P_4	AG12	
4	IO_L27N_4	AN7	
4	IO_L27P_4/VREF_4	AN6	
4	IO_L28N_4	AL10	
4	IO_L28P_4	AL9	
4	IO_L29N_4	AF12	
4	IO_L29P_4	AF13	
4	IO_L30N_4	AK10	
4	IO_L30P_4	AK11	
4	IO_L49N_4	AP7	
4	IO_L49P_4	AP6	
4	IO_L50N_4	AH13	
4	IO_L50P_4	AH12	
4	IO_L51N_4	AJ11	
4	IO_L51P_4/VREF_4	AJ12	
4	IO_L52N_4	AP9	
4	IO_L52P_4	AN8	
4	IO_L53N_4	AG13	
4	IO_L53P_4	AG14	
4	IO_L54N_4	AM11	
4	IO_L54P_4	AL11	
4	IO_L60N_4	AN10	NC
4	IO_L60P_4	AN9	NC

Table 13: **FF1517 BGA — XC2V4000, XC2V6000, and XC2V8000**

Bank	Pin Description	Pin Number	No Connect in the XC2V4000	No Connect in the XC2V6000
0	IO_L76P_0	C24		
0	IO_L77N_0	K22		
0	IO_L77P_0	K21		
0	IO_L78N_0	E22		
0	IO_L78P_0	E23		
0	IO_L79N_0	B23		
0	IO_L79P_0	B24		
0	IO_L80N_0	J22		
0	IO_L80P_0	J21		
0	IO_L81N_0	G21		
0	IO_L81P_0/VREF_0	G22		
0	IO_L82N_0	A23		
0	IO_L82P_0	A24		
0	IO_L83N_0	H22		
0	IO_L83P_0	H21		
0	IO_L84N_0	F21		
0	IO_L84P_0	F22		
0	IO_L91N_0/VREF_0	B21		
0	IO_L91P_0	B22		
0	IO_L92N_0	L20		
0	IO_L92P_0	M20		
0	IO_L93N_0	E21		
0	IO_L93P_0	D22		
0	IO_L94N_0/VREF_0	A21		
0	IO_L94P_0	A22		
0	IO_L95N_0/GCLK7P	H20		
0	IO_L95P_0/GCLK6S	J20		
0	IO_L96N_0/GCLK5P	C21		
0	IO_L96P_0/GCLK4S	D21		
1	IO_L96N_1/GCLK3P	F19		
1	IO_L96P_1/GCLK2S	F20		
1	IO_L95N_1/GCLK1P	H19		
1	IO_L95P_1/GCLK0S	H18		
1	IO_L94N_1	C19		
1	IO_L94P_1/VREF_1	C20		

BF957 Flip-Chip BGA Package

As shown in Table 14, XC2V2000, XC2V3000, XC2V4000, and XC2V6000 Virtex-II devices are available in the BF957 package. Pins in each of these devices are the same, except for the pin differences in the XC2V2000 device shown in the No Connect column. Following this table are the BF957 Flip-Chip BGA Package Specifications (1.27mm pitch).

Table 14: **BF957 — XC2V2000, XC2V3000, XC2V4000, and XC2V6000**

Bank	Pin Description	Pin Number	No Connect in XC2V2000
0	IO_L01N_0	H23	
0	IO_L01P_0	H22	
0	IO_L02N_0	G24	
0	IO_L02P_0	E25	
0	IO_L03N_0/VRP_0	B29	
0	IO_L03P_0/VRN_0	C27	
0	IO_L04N_0/VREF_0	F24	
0	IO_L04P_0	F23	
0	IO_L05N_0	D26	
0	IO_L05P_0	D25	
0	IO_L06N_0	A28	
0	IO_L06P_0	A27	
0	IO_L19N_0	J22	
0	IO_L19P_0	J21	
0	IO_L20N_0	G23	
0	IO_L20P_0	G22	
0	IO_L21N_0	B27	
0	IO_L21P_0/VREF_0	B26	
0	IO_L22N_0	K20	
0	IO_L22P_0	K19	
0	IO_L23N_0	C26	
0	IO_L23P_0	C24	
0	IO_L24N_0	D24	
0	IO_L24P_0	D23	
0	IO_L25N_0	E24	NC
0	IO_L25P_0	E23	NC
0	IO_L26N_0	G21	NC
0	IO_L26P_0	G20	NC
0	IO_L27N_0	A26	NC
0	IO_L27P_0/VREF_0	A25	NC
0	IO_L29N_0	H21	NC
0	IO_L29P_0	H20	NC
0	IO_L30N_0	B25	NC
0	IO_L30P_0	B23	NC

Table 14: **BF957 — XC2V2000, XC2V3000, XC2V4000, and XC2V6000**

Bank	Pin Description	Pin Number	No Connect in XC2V2000
3	IO_L93P_3	V1	
3	IO_L92N_3	U8	
3	IO_L92P_3	W8	
3	IO_L91N_3	U2	
3	IO_L91P_3	V2	
3	IO_L78N_3	U7	
3	IO_L78P_3	V7	
3	IO_L77N_3	U4	
3	IO_L77P_3	V4	
3	IO_L76N_3	W1	
3	IO_L76P_3	Y1	
3	IO_L75N_3/VREF_3	V5	
3	IO_L75P_3	W5	
3	IO_L74N_3	W2	
3	IO_L74P_3	Y2	
3	IO_L73N_3	W6	
3	IO_L73P_3	Y6	
3	IO_L72N_3	Y5	
3	IO_L72P_3	AA5	
3	IO_L71N_3	W3	
3	IO_L71P_3	Y3	
3	IO_L70N_3	W4	
3	IO_L70P_3	Y4	
3	IO_L69N_3/VREF_3	U9	
3	IO_L69P_3	V9	
3	IO_L68N_3	AA1	
3	IO_L68P_3	AB1	
3	IO_L67N_3	Y7	
3	IO_L67P_3	AA7	
3	IO_L54N_3	AA6	
3	IO_L54P_3	AC6	
3	IO_L53N_3	AA2	
3	IO_L53P_3	AB2	
3	IO_L52N_3	AA4	
3	IO_L52P_3	AC4	
3	IO_L51N_3/VREF_3	V10	
3	IO_L51P_3	W10	
3	IO_L50N_3	AA3	

Table 14: **BF957 — XC2V2000, XC2V3000, XC2V4000, and XC2V6000**

Bank	Pin Description	Pin Number	No Connect in XC2V2000
NA	DXP	B28	
NA	VBATT	D5	
NA	RSVD	B4	
NA	VCCAUX	B16	
NA	VCCAUX	C2	
NA	VCCAUX	C30	
NA	VCCAUX	T2	
NA	VCCAUX	T30	
NA	VCCAUX	AJ2	
NA	VCCAUX	AJ30	
NA	VCCAUX	AK16	
NA	VCCINT	K15	
NA	VCCINT	K17	
NA	VCCINT	L11	
NA	VCCINT	L16	
NA	VCCINT	L21	
NA	VCCINT	M12	
NA	VCCINT	M16	
NA	VCCINT	M20	
NA	VCCINT	N13	
NA	VCCINT	N14	
NA	VCCINT	N15	
NA	VCCINT	N16	
NA	VCCINT	N17	
NA	VCCINT	N18	
NA	VCCINT	N19	
NA	VCCINT	P13	
NA	VCCINT	P19	
NA	VCCINT	R10	
NA	VCCINT	R13	
NA	VCCINT	R19	
NA	VCCINT	R22	
NA	VCCINT	T11	
NA	VCCINT	T12	
NA	VCCINT	T13	
NA	VCCINT	T19	
NA	VCCINT	T20	